

SOT993-1

plastic thermal enhanced very thin quad flat package; no leads; 28 terminals

8 February 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN28
Package type industry code	HVQFN28
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
IEC package outline code	---
JEDEC package outline code	MO-220
JEITA package outline code	---
Mounting method type	S (surface mount)
Issue date	8-3-2007

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	4.9	-	5	5.1	mm
E	package width	4.9	-	5	5.1	mm
A	seated height	[tbd]	-	[tbd]	0.9	mm
e	nominal pitch	-	-	0.5	-	mm
n ₂	actual quantity of termination	-	-	28	-	

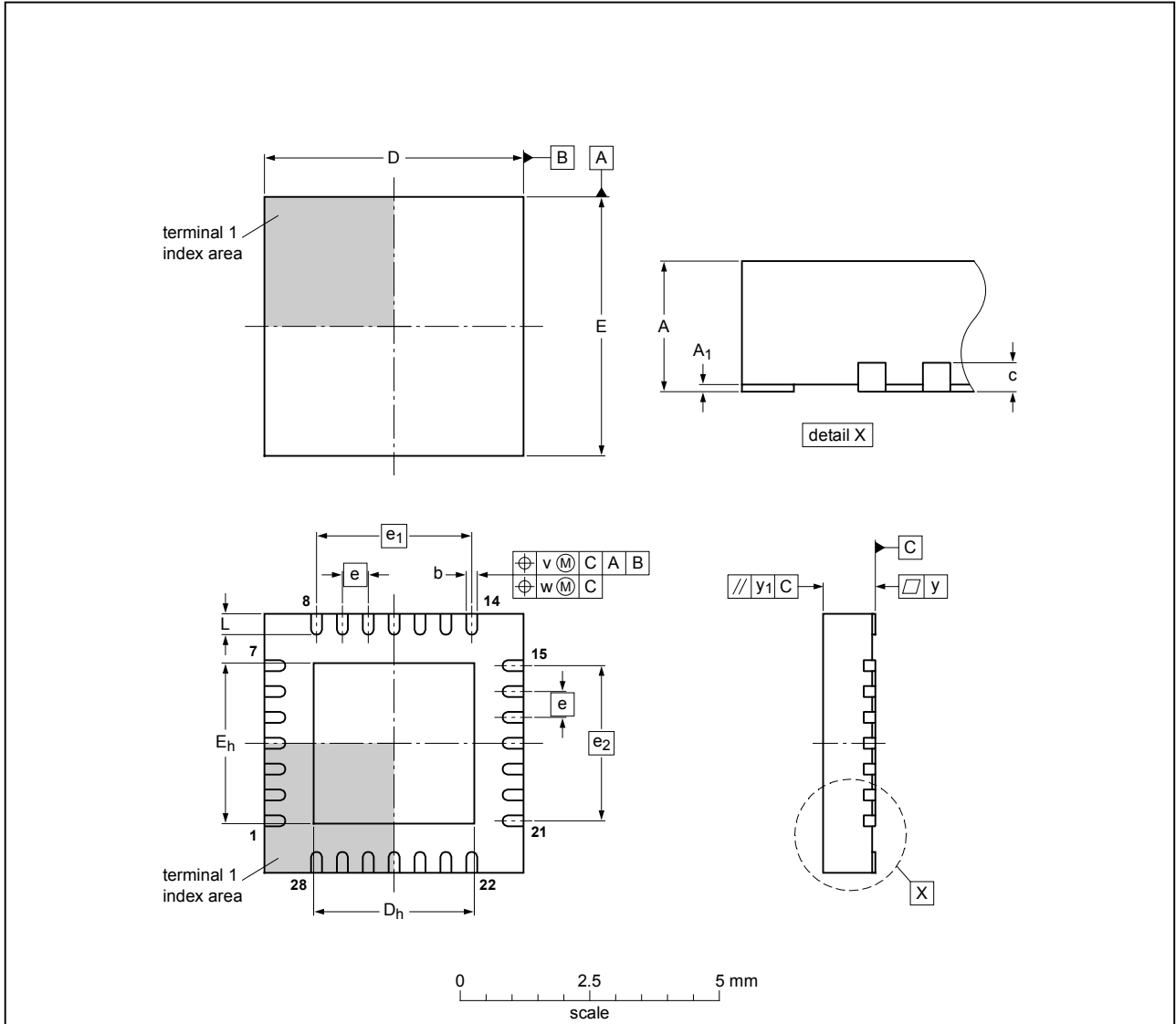


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2. Package outline

HVQFN28: plastic thermal enhanced very thin quad flat package; no leads; 28 terminals; body 5 x 5 x 0.85 mm

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DIMENSIONS (mm are the original dimensions)

UNIT	A ⁽¹⁾ max	A ₁	b	c	D ⁽¹⁾	D _n	E ⁽¹⁾	E _n	e	e ₁	e ₂	L	v	w	y	y ₁
mm	0.9	0.05 0.00	0.30 0.18	0.2	5.1 4.9	3.25 2.95	5.1 4.9	3.25 2.95	0.5	3	3	0.5 0.3	0.1	0.05	0.05	0.1

Note

1. Plastic or metal protrusions of 0.075 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT993-1	---	MO-220	---			07-02-13 07-03-08

Fig. 1. Package outline HVQFN28 (SOT993-1)

3. Legal information

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